



INTERNATIONAL ATOMIC ENERGY AGENCY
UNITED NATIONS EDUCATIONAL, SCIENTIFIC AND CULTURAL ORGANIZATION



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H4.SMR/285 - 40

WINTER COLLEGE ON
LASER PHYSICS: SEMICONDUCTOR LASERS
AND INTEGRATED OPTICS

(22 February - 11 March 1988)

INTEGRATED OPTICS

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CSELT
Torino, Italy

ICTP WINTER COLLEGE 1988 :

SEMICONDUCTOR LASERS AND
INTEGRATED OPTICS

INTEGRATED OPTICS :

COMPONENTS AND DEVICES II

- ACTIVE DEVICES
- MULTIFUNCTIONAL DEVICES

C. DE BERNARDI
CSELT - TORINO (I)

ACTIVE DEVICES FOR
INTEGRATED OPTICS

- LASER SOURCES
- AMPLIFIERS
- PHOTODETECTORS
- POLARIZATION CONTROLLERS
- TUNABLE FILTERS / SPLITTERS

MAIN INTEREST FOR ACTIVE DEVICES :

- POSSIBILITY OF FULLY MONOLITHICAL INTEGRATION OF COMPLETE UNITS, SUCH AS:
 - TRANSMITTERS
 - RECEIVERS
 - SIGNAL REGENERATORS / PROCESSORS
 - DEVICES WITH INTERNAL OPTICAL AMPLIFICATION

OPTICAL INTEGRATED SOURCES

MAIN REQUIREMENTS:

- STRUCTURES MUST BE ARBITRARILY PLACED ON SUBSTRATE (NOT NECESSARILY ON CHIP EDGE)
- FABRICATION STEPS MUST BE COMPATIBLE WITH FABRICATION OF OTHER COMPONENTS AND DEVICES (OPTICAL AND/OR ELECTRONIC)

DIRECT CONSEQUENCES:

- CONVENTIONAL CLEAVED-FACET MIRRORS ARE NOT USABLE FOR LASER RESONATORS
- MULTI-STEP EPITAXIAL PROCESSES ARE REQUIRED
- STRUCTURES COMPATIBLE WITH SEMI-INSULATING SUBSTRATES ARE REQUIRED IN SOME CASES
- OUTPUT WAVEGUIDE MUST BE OF DIFFERENT COMPOSITION FROM ACTIVE LAYER FOR LOW LOSS (ACTIVE LAYER IS STRONGLY ABSORBING WHEN NOT PUMPED)

INTEGRATED LASERS

TECHNIQUES FOR RESONATOR FABRICATION

LOCALIZED MIRRORS:

- ETCHED MIRRORS
 - BY CHEMICAL ETCHING
 - BY ION MILLING

- MICROCLEAVED MIRRORS: BY ULTRASONIC CLEAVING OF BRIDGE/CANTILEVER STRUCTURES

DISTRIBUTED MIRRORS:

- DISTRIBUTED BRAGG REFLECTORS (GRATING OUTSIDE GAIN REGION)
- DISTRIBUTED FEEDBACK (GRATING INSIDE THE GAIN REGION)

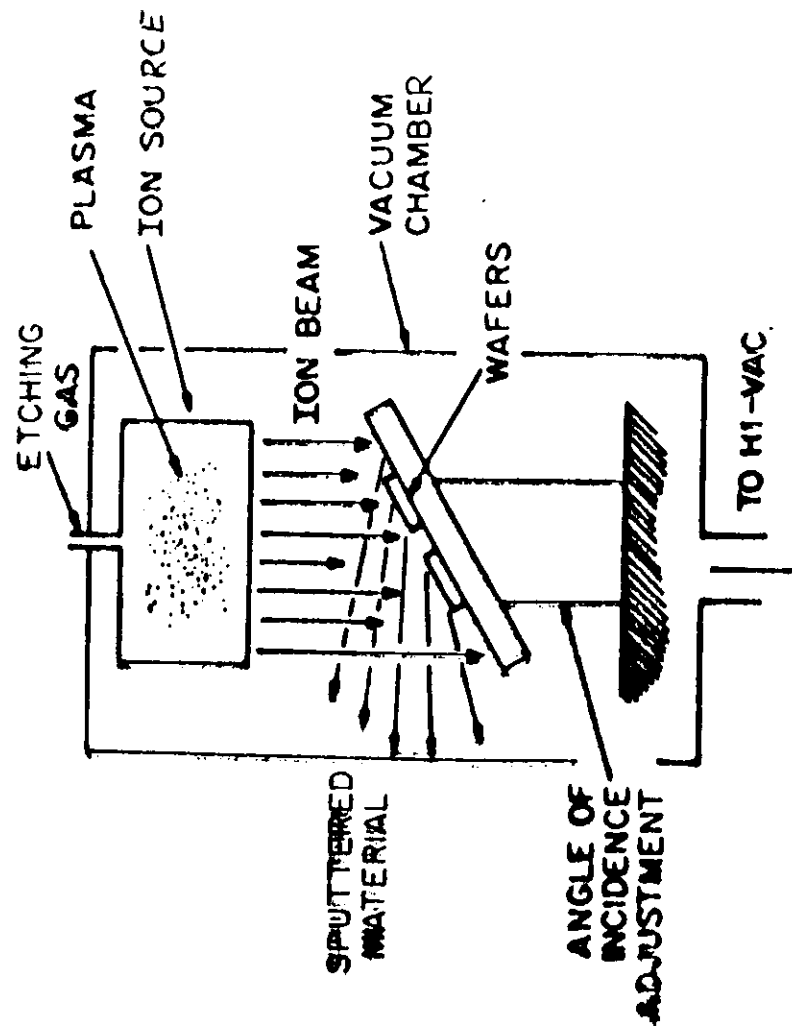
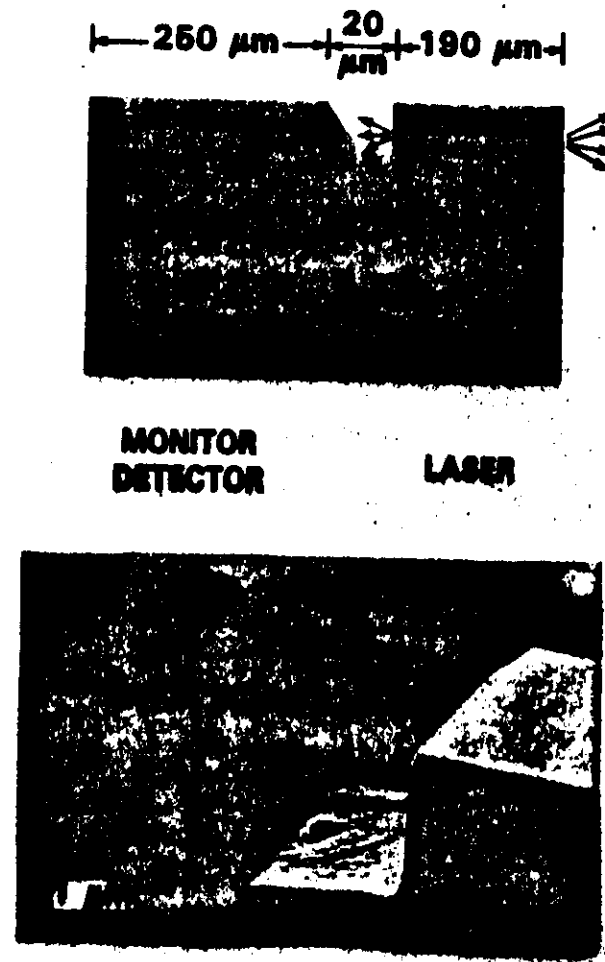
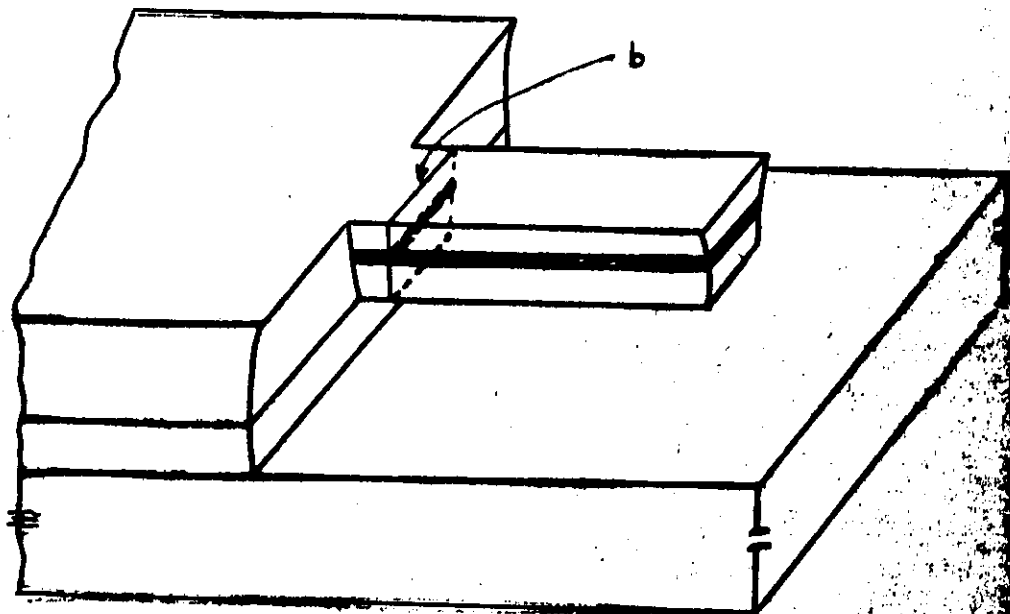


Fig. 5. Inert ion beam milling system. Samples may be tilted and/or rotated w the incident ion beam.

LASER CON MONITOR INTEGRATO



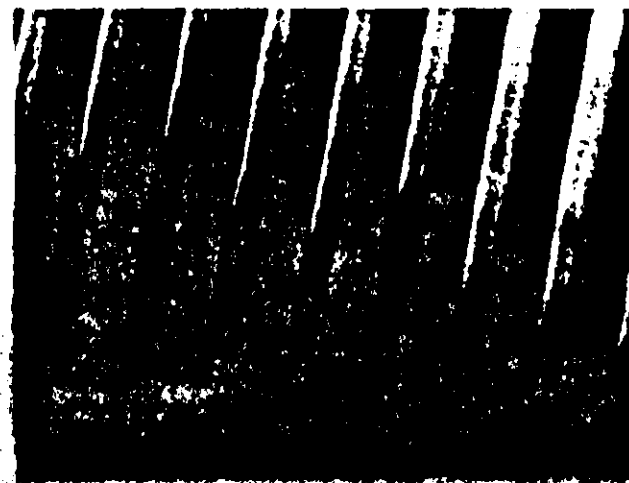
MICROCLEAVED - FACET - MIRROR INTEGRATED LASERS



a) AFTER SELECTIVE ETCHING A CANTILEVER
STRUCTURE IS DEFINED

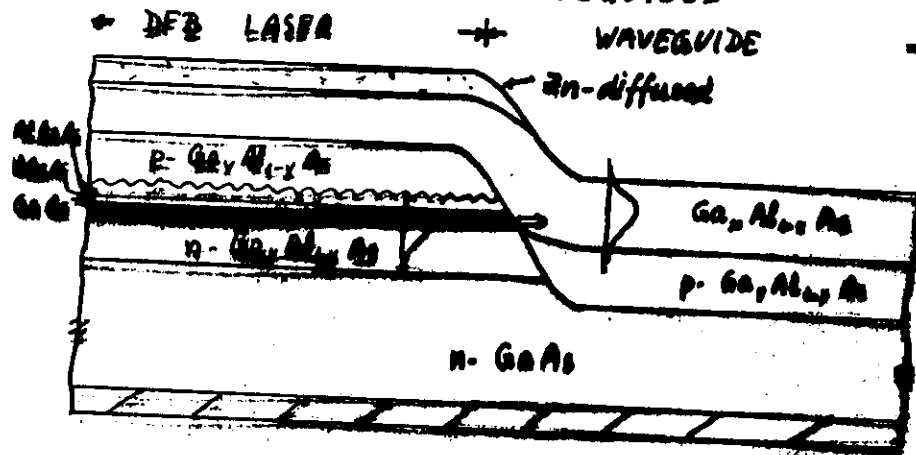
b) AFTER ULTRASONIC PROCESSING A SHORT,
WELL-CLEAVED PROTRUDING MIRROR IS LEFT

HOLOGRAPHIC GRATINGS EXPOSED IN PHOTORESIST

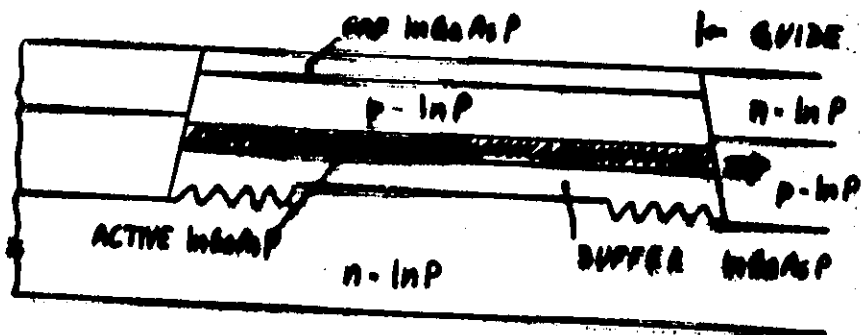


INTEGRATED LASERS

STRUCTURES FOR EFFICIENT COUPLING
TO LOW-LOSS WAVEGUIDES



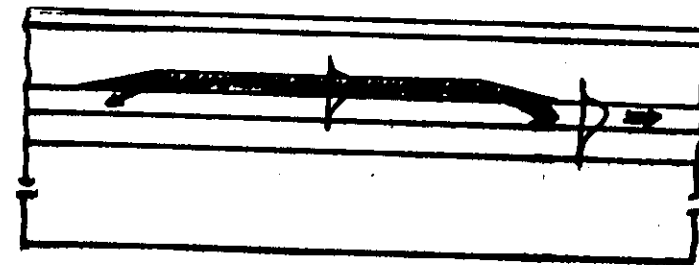
g) INTEGRATED DFB LASER + GUIDE, DIRECT COUPLING



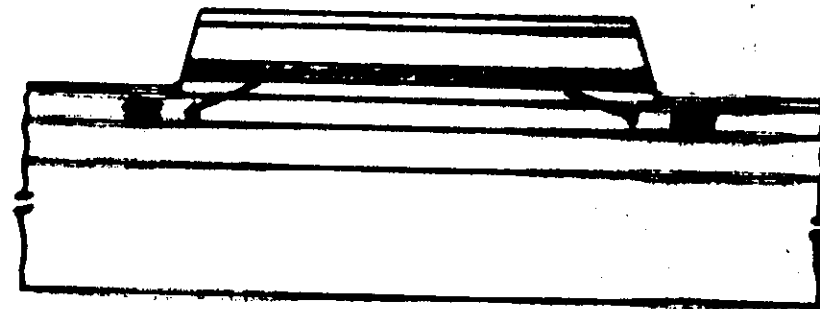
h) INTEGRATED DBR LASER + GUIDE, DIRECT COUPLING

INTEGRATED LASERS

STRUCTURES FOR EFFICIENT COUPLING
TO LOW-LOSS WAVEGUIDES



c) LASER TAPER-COUPLED TO THE GUIDE



d) LASER EVANESCENT-COUPLED TO THE GUIDE

INTEGRATED OPTICAL AMPLIFIERS

THE FUNDAMENTAL STRUCTURE IS SIMILAR TO AN INTEGRATED LASER

TWO MAIN CLASSES OF AMPLIFIERS:

- RESONANT AMPLIFIERS
- TRAVELLING-WAVE (TW) AMPLIFIERS

REQUIREMENTS

RESONANT TYPE: MIRROR REFLECTIVITY 1 - 5%

TW TYPE: " " < 0.1%

STRUCTURES AND RELATIVE FEATURES

RESONANT: REDUCED REFLECTIVITY

- | | | |
|---|---|---|
| <ul style="list-style-type: none">• COATED FACETS• SHALLOW GRATING DBR OR PBR• LOW DB TO BUTT-COUPLED GUIDE | } | LOW NOISE
LOW GAIN
SELECTIVE (FWHM) |
|---|---|---|

TW: STRONGLY REDUCED REFLECTIVITY

- | | | |
|---|---|-------------------------|
| <ul style="list-style-type: none">• HIGH PERFORMANCE AR COATING• EMBEDDED STRUCTURE WITH | } | HIGH GAIN
HIGH NOISE |
|---|---|-------------------------|

INTEGRATED OPTICAL DETECTORS

- MANY STRUCTURES COMPATIBLE WITH INPUT FROM WAVEGUIDE
- MUCH LESS CRITICAL PROBLEMS THAN FOR SOURCE INTEGRATION
- SUITABLE MATERIALS: SILICON (FOR $\lambda < 1 \mu\text{m}$)
InGaAs/InP (FOR 1.3 - 4.6 μm)
- GENERAL FEATURES:
 - HIGH BANDWIDTH / LOW SIZE (SEVERAL μm^2)
 - HIGH INTERNAL QUANTUM EFFICIENCY ($\eta \approx 100\%$)
 - EASY INTEGRATION WITH ELECTRONICS (SI-BASED)
 - DETECTORS CAN BE MADE ON PASSIVE MATERIALS (E.G. GLASS) BY USE OF LOCAL AMORPHOUS Si DEPOSITION

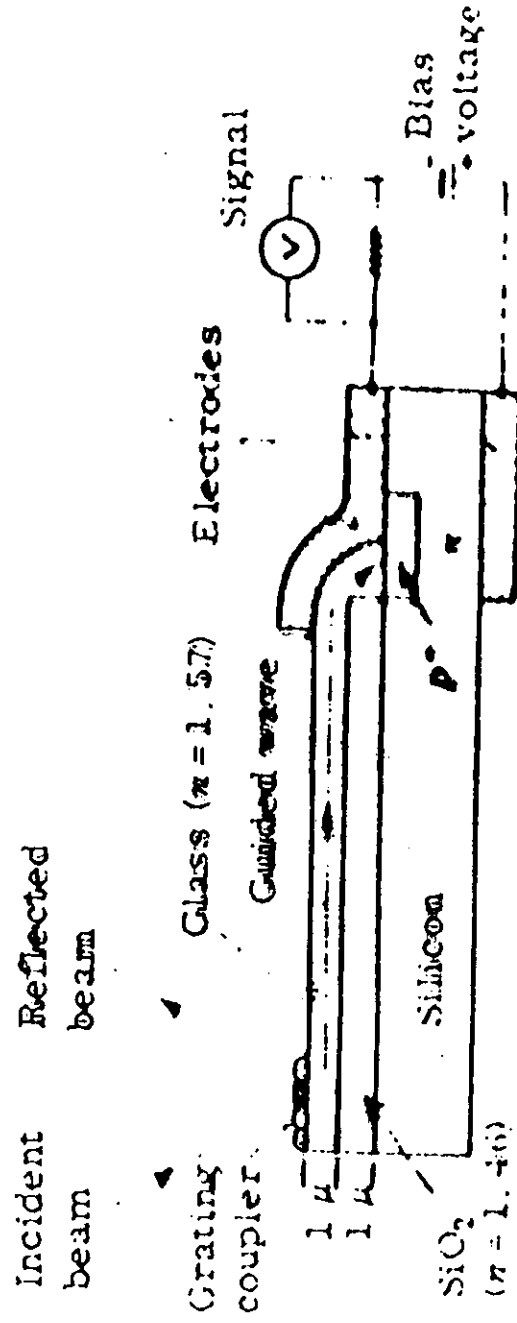
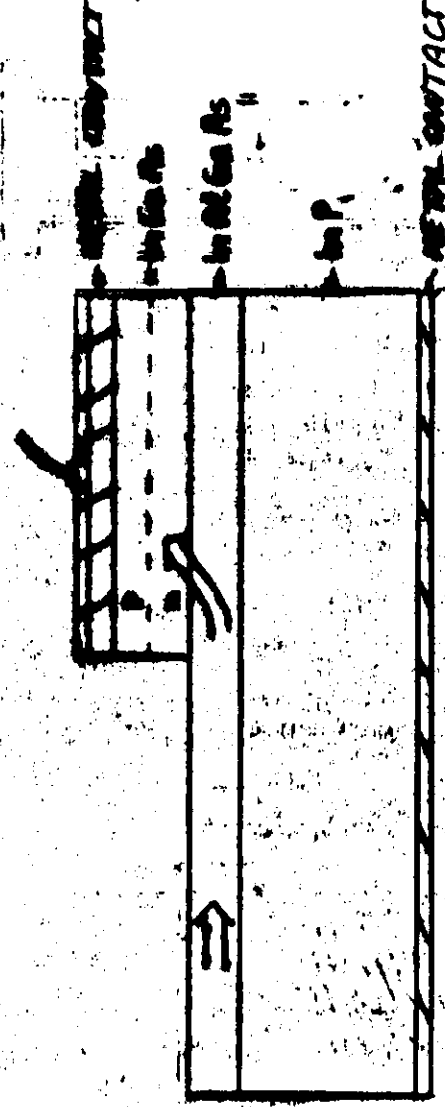
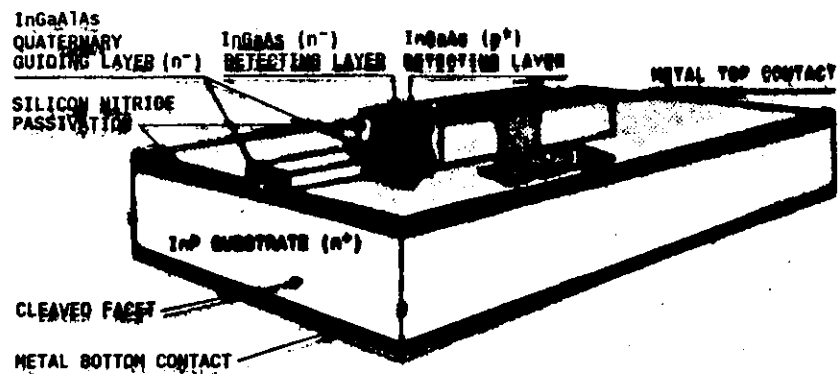


FIG. 1. Photo-electrically integrated photodetector schematic.

4-4 optical
switch with
switch

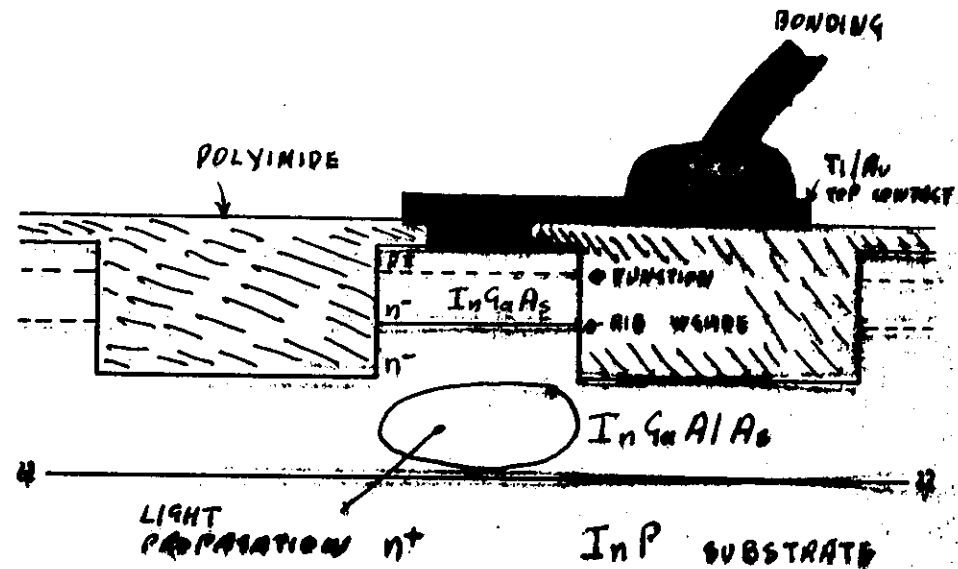


SCHEMATIC STRUCTURE OF A PHOTO-ELECTRICALLY INTEGRATED PHOTODETECTOR



HIGH QUANTUM EFFICIENCY¹¹ INTEGRATED W4WIDE-PD_s
 $\eta_{\text{int}} \sim 80-100\%$ $\lambda = 1.55 \mu\text{m}$

HIGH BANDWIDTH InGaAlAs INTEGRATED PHOTODIODES - SCHEMATIC CROSS SECTION



DIODE LENGTH: 200, 300, 400 μm
 DIODE WIDTH: 10, 15, 20, 35 μm
 InGaAs THICKNESS: 2-3 μm (p+ + n-)
 InGaAlAs AD WIDTH: 10, 20, 30 μm
 CONTACT PAD AREA: 50 x 50 μm^2

As-Si
 BOTTOM
 CONTACT

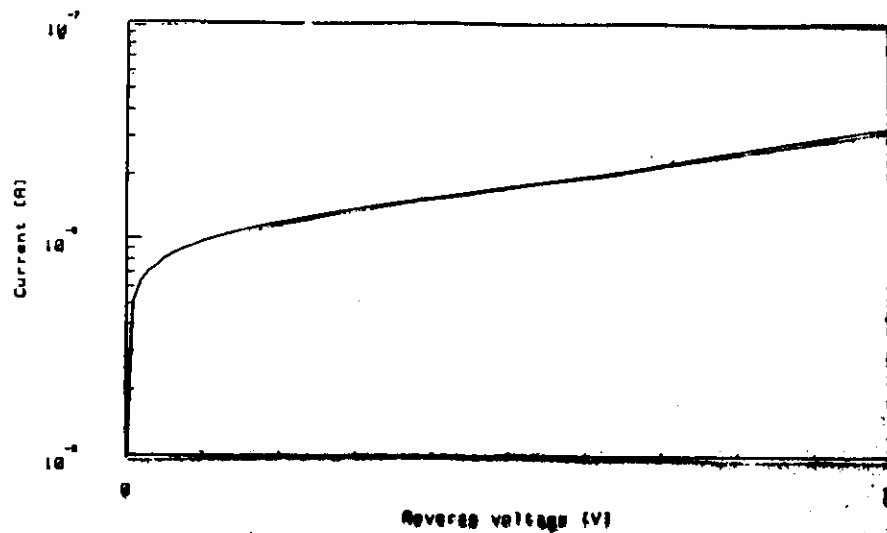


Fig. 9: Reverse I/V characteristic of a high-speed device.



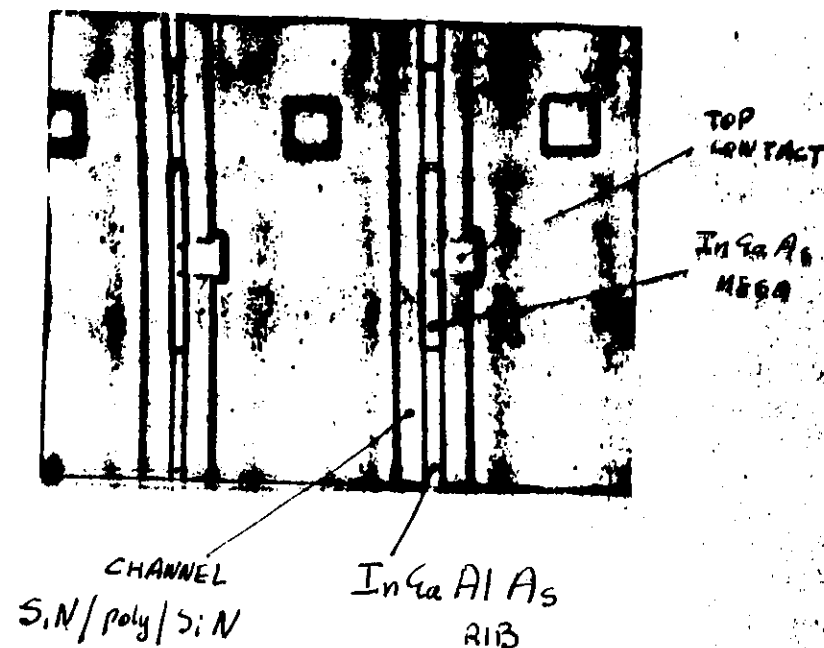
Fig. 10: Optical micrograph of a high-speed device.

$$C(V=0) < 0.5 \text{ pF}$$

$$\text{typical: } 0.2 \sim 0.35 \text{ pF}$$

$$\Delta f(\text{intrinsic}) = 1/\pi RC = 18 \sim 30 \text{ GHz}$$

$$R = 50 \Omega$$



MULTIFUNCTIONAL DEVICES

OPTICAL INTEGRATION ALLOWS FABRICATION
ON A SINGLE CHIP OF COMPONENTS AND
DEVICES FOR DIFFERENT FUNCTIONS:

EXAMPLES:

- LASER SOURCE + MONITORING DETECTOR
- LASER + SEPARATED MODULATOR (ν, ϕ, λ)
- MULTIPLE LASERS WITH DIFFERENT λ
- MULTICAVITY LASERS
- LASERS + MULTIPLEXER
- DEMULTIPLEXER + DETECTORS
- POLARIZATION TRANSFORMERS + SPLITTERS
- MIXERS, COUPLERS, FILTERS + SQUARES + DETECTORS
- ALL COMBINATIONS OF THE ABOVE COMPONENTS
- OPTICAL + ELECTRONIC COMPONENTS (PET, NIST, ...)
- ARRAYS OF COMPONENTS

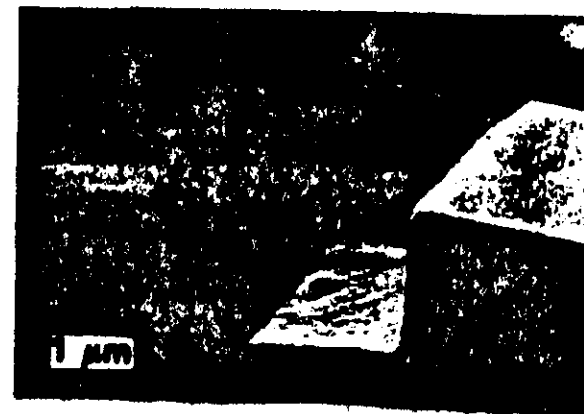
LASER CON MONITOR INTEGRATO

250 μm 20 μm 190 μm

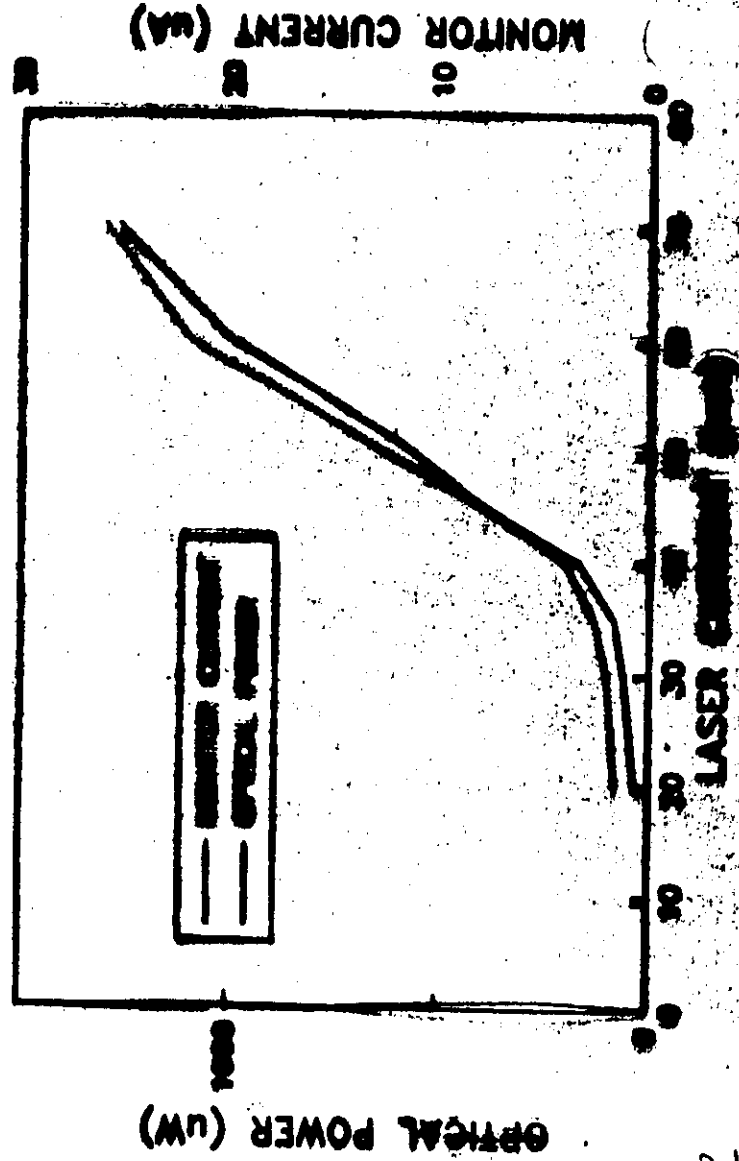


MONITOR
DETECTOR

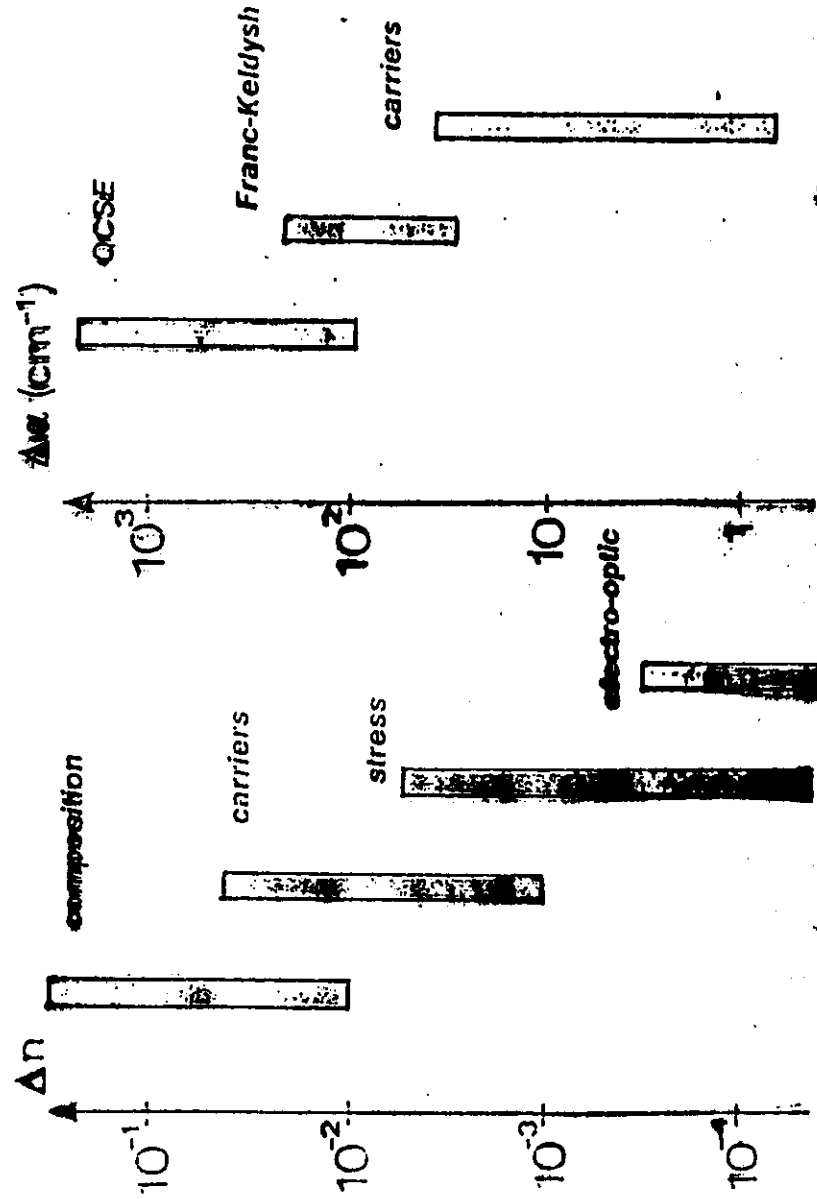
LASER

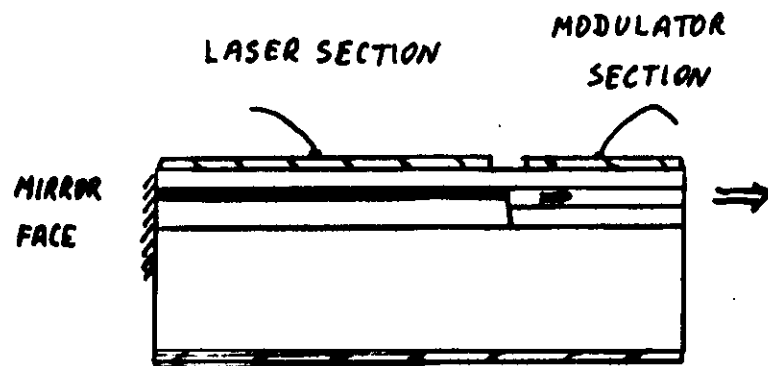


MUSHROOM LASER - MONITOR WITH RIBE FACET



EFFECTS USABLE FOR TUNING AND MODULATION IN INTEGRATED OPTICS ON III-V COMPOUNDS





INTEGRATED LASER + MODULATOR :

a) Δn MODULATION IN MOD. SECTION :

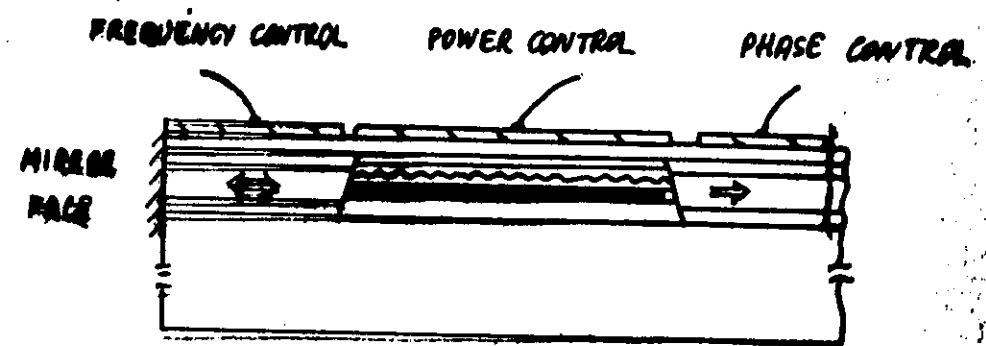
FREQUENCY MODULATED, CONSTANT AMPLITUDE

b) α MODULATION IN MOD. SECTION :

AMPLITUDE MODULATED SOURCE

ADVANTAGES :

- HIGHER SPECTRAL STABILITY THAN FOR DIRECTLY MODULATED LASER AT HIGH FREQUENCIES
- FINE TUNING OF LASER FREQUENCY



INTEGRATED MULTICAVITY SOURCE WITH FULL SPECTRAL CONTROL

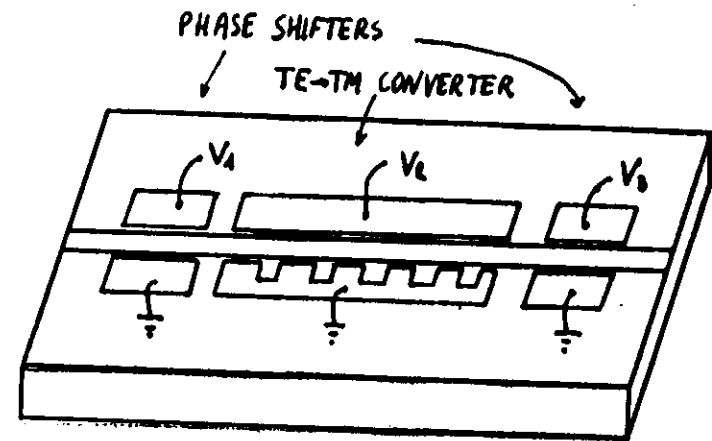
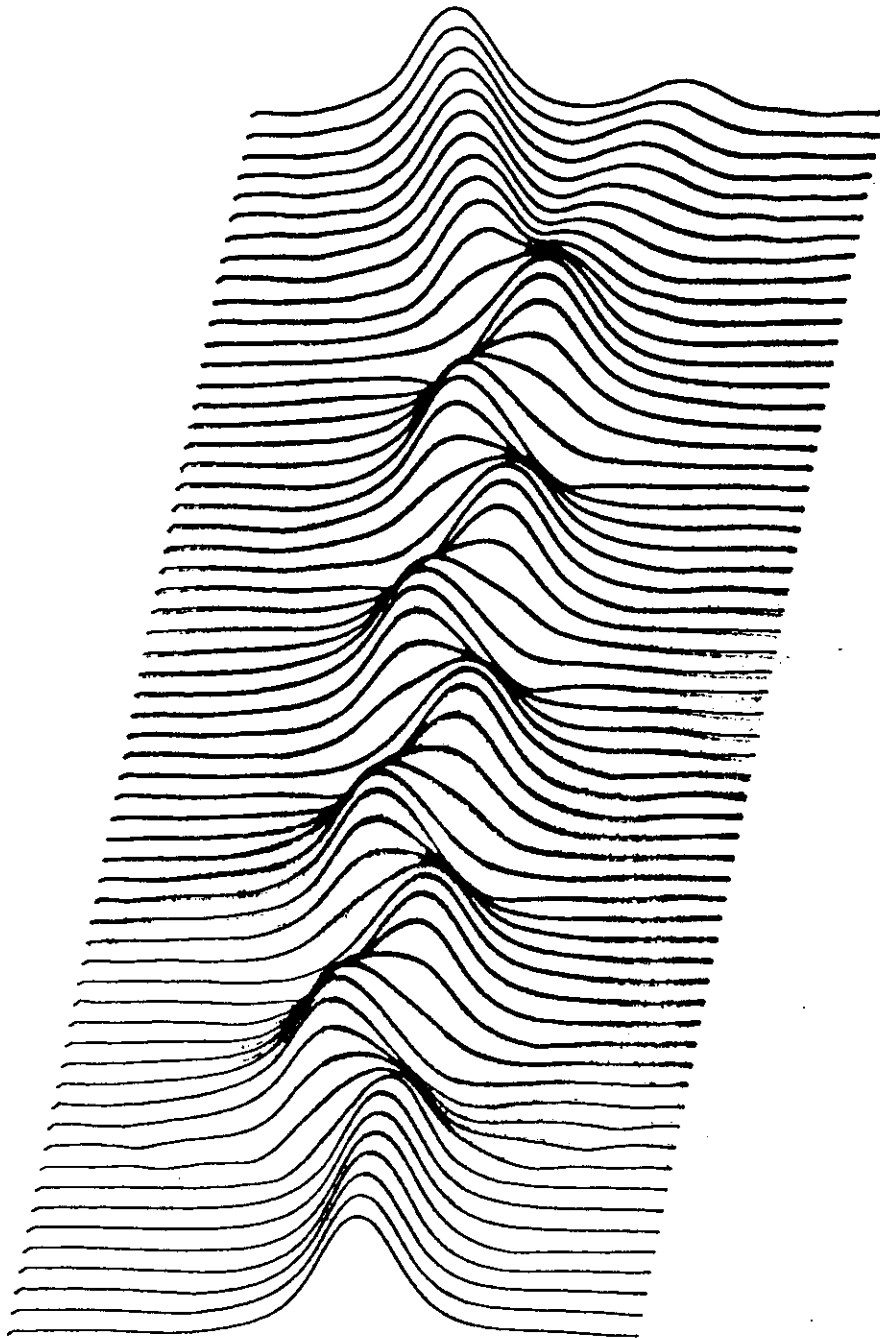
a) POWER CONTROL BY INJECTION CURRENT IN DFB LASER SECTION

b) FREQUENCY CONTROL BY ELECTRO-OPTIC OR CARRIER-DENSITY CHANGE OF n IN THE COUPLED CAVITY SECTION

c) PHASE CONTROL BY SAME EFFECTS IN A SECTION OF THE OUTPUT GUIDE

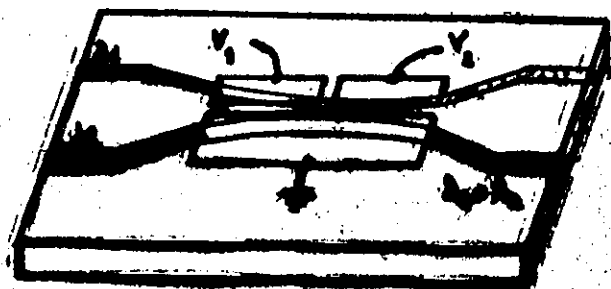
ADVANTAGES :

- INDEPENDENT CONTROL OF ALL THE PARAMETERS OF THE OPTICAL WAVE
- HIGH OPERATION STABILITY IN THE REQUIRED RANGE
- MUCH HIGHER SPECTRAL STABILITY THAN EQUIVALENT HYBRID STRUCTURES



POLARIZATION CONVERTER

- PHASE SHIFTERS CHANGE RELATIVE PHASE BETWEEN TE AND TM WAVE BY V_1 AND V_3
- PERIODIC ELECTRODE TRANSFERS POWER BETWEEN TE AND TM WAVE WITH EFFICIENCY SET BY V_2



TUNABLE DIRECTIONAL COUPLER DEMULTIPLEXER



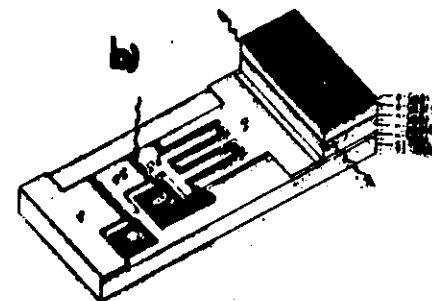
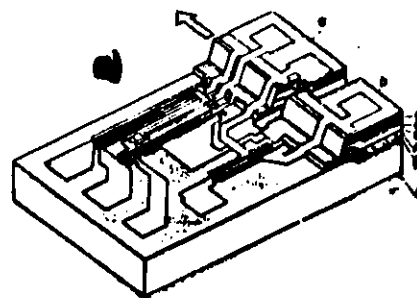
MULTICHANNEL DEMULTIPLEXER



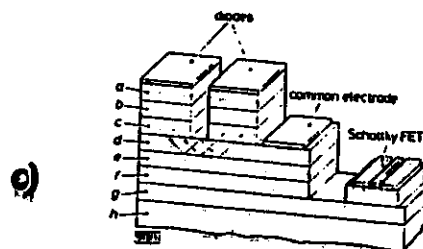
BRAGG GRATINGS

BRAGG FILTER DEMULTIPLEXED RECEIVER

EXAMPLES OF MONOLITHIC OPTOELECTRONIC INTEGRATION



a Laser, b Photodiode, c GaAs, d GaAlAs, e GaAlAs active layer, f GaAlAs, g GaAs waveguide layer, h Semi-insulating GaAs

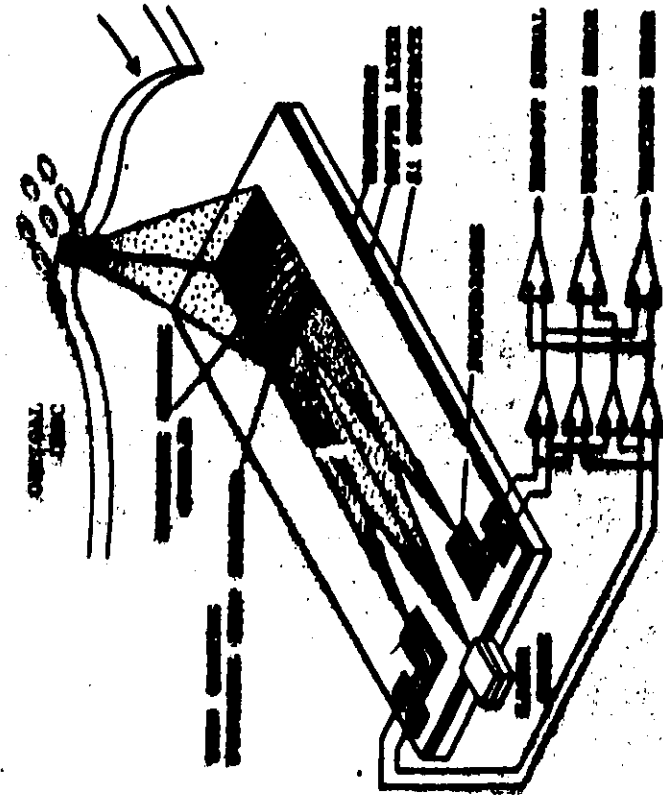
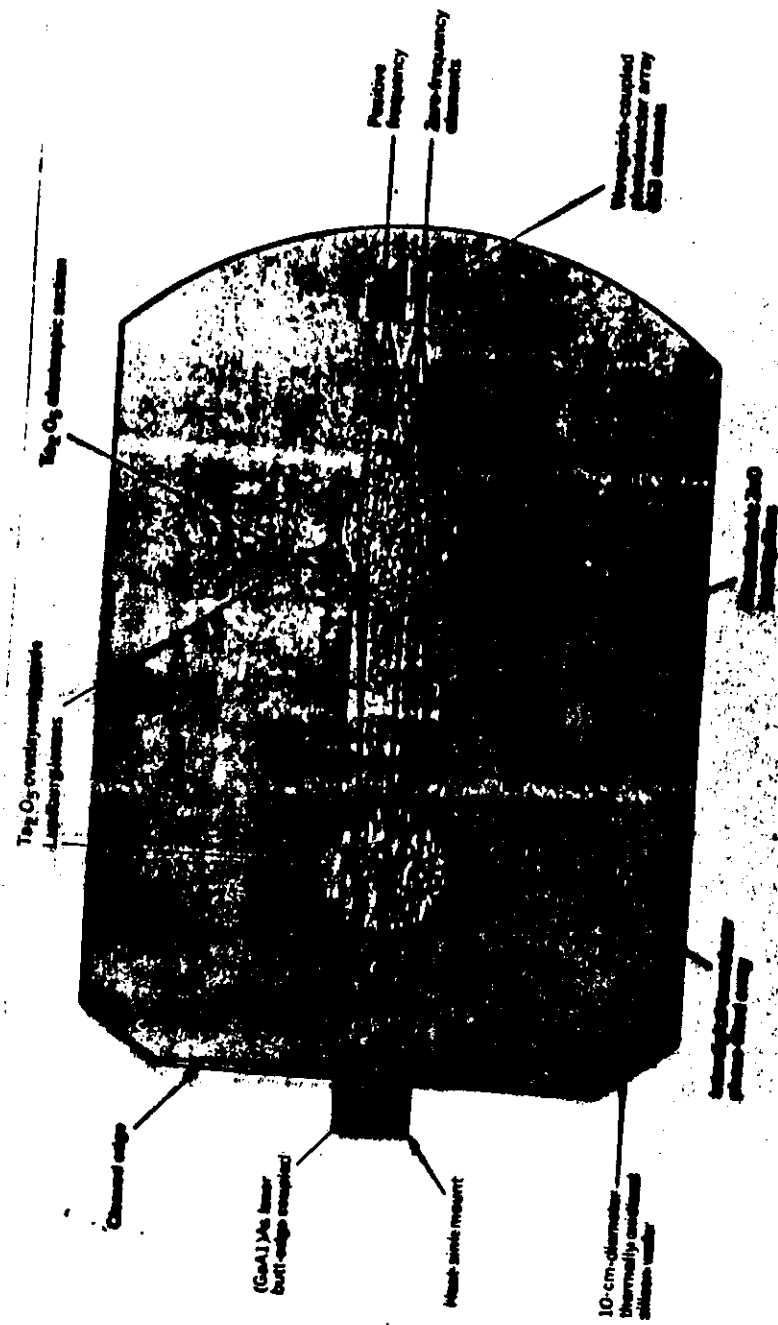


a p-GaAs cap layer
b p-GaAs, Al_{0.3}As upper guide
c n-GaAs active layer
d n-GaAs, Al_{0.3}As lower guide
e n-GaAs, Al_{0.3}As buffer layer
f n-GaAs FET layer

a) TRANSMITTER

b) REPEATER

c) MULTI-PURPOSE CIRCUIT



Schematic view of the proposed tapered-optic disc pickup device.